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By: Werner Steiner

Date: March 17, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Lothar Bauch et al. /
Applic. No. : 10/082,554 /
Filed : February 25, 2002 /
Title : Stacked VIA with Specially Designed Landing Pad for Integrated Semiconductor Structures
Examiner : Pershelle L. Greene Group Art Unit: 2826

TECHNOLOGY CENTER 2800
MAR 26 2003

#11
Translation
JMcClunell
6/11/03

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LETTER

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

Sir:

As indicated on page 8, third paragraph, of counsel's amendment filed in the Patent Office on January 13, 2003, enclosed please find a certified translation of the German priority application number 199 39 852.6, filed August 23, 1999. A claim for priority is also enclosed.

Respectfully submitted,

Werner Steiner

For Applicants

/tk

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March 17, 2003

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